

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image





Similar to illustration

The new benchmark for component density: the virtual 0.875mm pitch - for 1mm² I/O connections

The only 4-row double level male connectors for standard IP20 sensor interfaces with 3.5 pitch

The S2L in a double pack - a standard has surpassed itself:

- Each 3.5mm wide, 4 I/O contacts for 1mm² connection cross-section
- Force-fit enclosure geometry guarantees maximum stability
- · Solder flange eliminates the need for a screw fastening

Less is more - basic advantages for your applications:

- 75% space savings on the circuit board
- Solder flange reduces process costs
- Less mechanical load on the soldering points
- More space for displays in the front panel, for example

A "small" contribution to greater competitiveness: additional features in the same installation space or a more compact device with the same range of functions.

General ordering data

Packaging	Box
Product data	IEC: 200 V / 7.9 A UL: 150 V / 9.5 A
Qty.	20 pc(s).
GTIN (EAN)	4050118160901
Туре	S2CD-THR 3.50/24/90LF 3.2SN BK BX
Order No.	<u>1357940000</u>
Version	PCB plug-in connector, male header, closed side / solder flange, THT/THR solder connection, 3.50 mm, Number of poles: 24, 90°, Solder pin length (I): 3.2 mm, tinned, black, Box



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Technical data

Depth	24.4 mm	Depth (inches)	0.961 inch
Height	35 mm	Height (inches)	1.378 inch
Height of lowest version	31.8 mm	Net weight	15 g
Width	28 mm	Width (inches)	1.102 inch

System specifications

Product family	OMNIMATE Signal - series B2C/S2C 3.50 - 2-row	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	0.5
	connection		3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	90°
Number of poles	24	Number of solder pins per pole	1
Solder pin length (I)	3.2 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D)+ 0,1 mm	
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	38.5 mm	L1 in inches	1.516 inch
Pin series quantity		Touch-safe protection acc. to DIN VI	DE
	2	57 106	Safe from finger touch
Touch-safe protection acc. to DIN VI	DE	Can be coded	
0470	IP 20		Yes

Material data

Insulating material	LCP GF
Colour chart (similar)	RAL 9011
Comparative Tracking Index (CTI)	≥ 175
UL 94 flammability rating	V-0
Contact surface	
	tinned
Layer structure of plug contact	tinned 25 μm Sn / 13 μm Ni
Layer structure of plug contact Storage temperature, max.	
, 18	25 µm Sn / 13 µm Ni
Storage temperature, max.	25 μm Sn / 13 μm Ni 70 °C

Colour	black
Insulating material group	IIIb
Moisture Level (MSL)	1
Contact material	Copper alloy
Layer structure of solder connection	13 µm Ni / 25 µm Sn
	matt
Storage temperature, min.	-40 °C
Operating temperature, min.	-50 °C
Temperature range, installation, min.	-40 °C

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	7.9 A
Rated current, max. number of poles (Tu=20°C)	5 A	Rated current, min. number of poles (Tu=40°C)	6.8 A
Rated current, max. number of poles Tu=40°C)	5 A	Rated voltage for surge voltage class / pollution degree II/2	200 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	100 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	1.5 kV	Short-time withstand current resistance	3 x 1s with 80 A



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Technical data

Institute (CSA)	6	Certificate No. (CSA)	
	S.		200020 1121600
Rated voltage (Use group B / CSA)	50 V	Rated voltage (Use group C / CSA)	200039-1121690 50 V
Rated voltage (Use group D / CSA)	150 V	Rated current (Use group B / CSA)	50 V 5 A
	9.5 A	Rated current (Use group D / CSA)	9.5 A
Rated current (Use group C / CSA)		Rated current (Use group D / CSA)	9.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
Institute (cURus)		Certificate No. (cURus)	
	CH		500000
			E60693
Rated voltage (Use group B / UL 1059)		Rated voltage (Use group C / UL 1059)	
Rated voltage (Use group D / UL 1059)		Rated current (Use group B / UL 1059)	
Rated current (Use group C / UL 1059)		Rated current (Use group D / UL 1059)	9.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
Packaging	Box	VPE length	45 mm
VPE width	130 mm	VPE height	145 mm
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
Important note			
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		
Notes	Gold-plated contact surfaces o	n request	
	Rated current related to rated of	cross-section & min. No. of poles.	
	Spacing between rows: see ho	ble layout	
	• P on drawing = pitch		
		mponent itself. Clearance and creepage distance the relevant application standards.	ces to other components are to
	Long term storage of the produ	uct with average temperature of 50 °C and aver	age humidity 70%, 36 months



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Germany

Technical data

Approvals	
Approvals	
ROHS	Conform
UL File Number Search	E60693
Downloads	
Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	STEP

Drawings

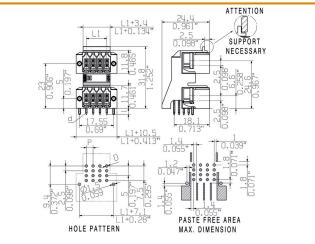


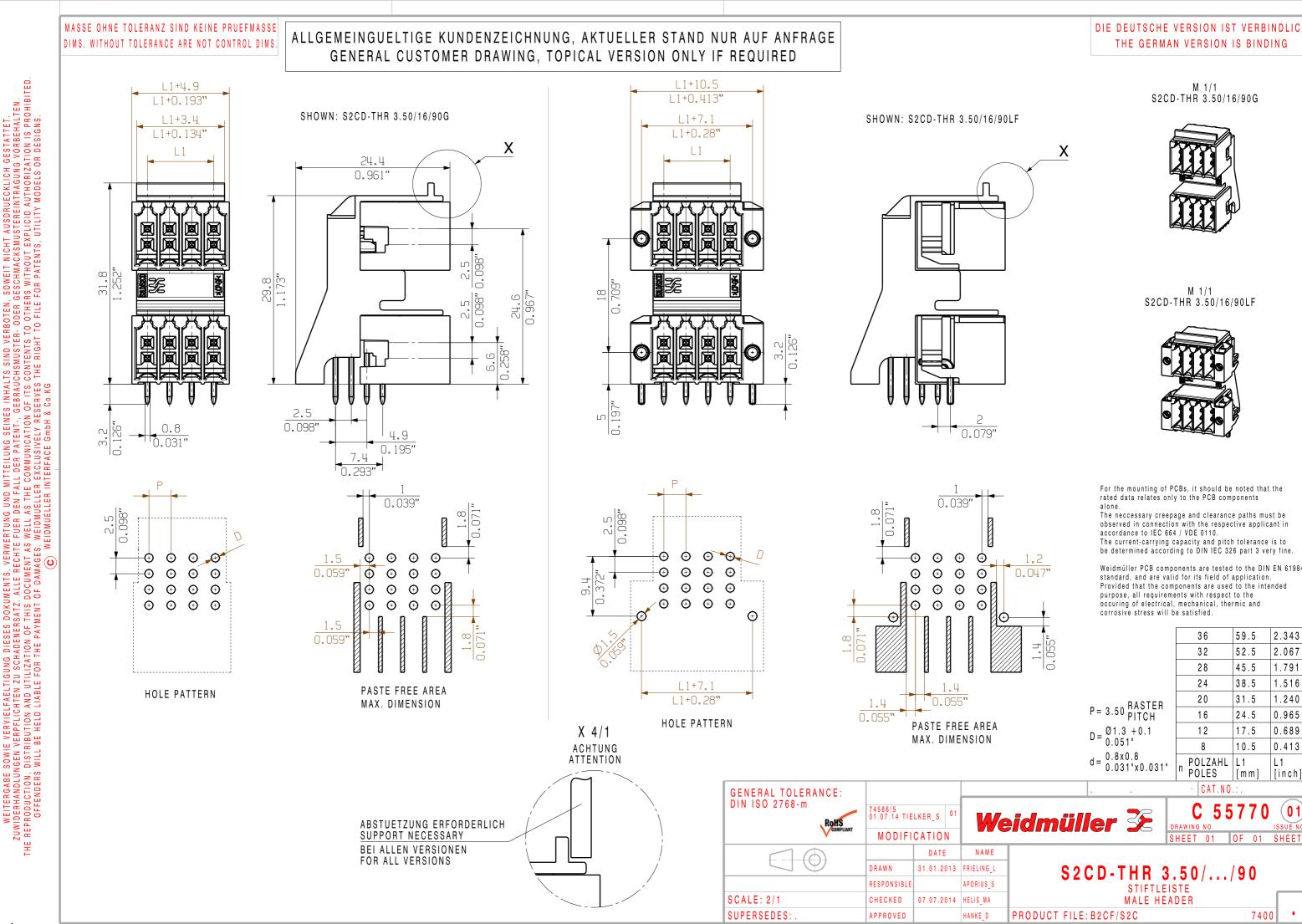
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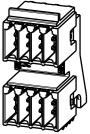
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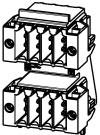
Dimensional drawing





DIE DEUTSCHE VERSION IST VERBINDLICH





Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.

2.343 2.067 1.791 1.516 1.240 0.965 0.689 0.413



Wave Solder Profile

Recommended wave solderding profiles

Weidmüller 🟵

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Klingenbergstraße 16 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com



Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile



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Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.